

IEEE Components, Packaging and Manufacturing Technology Society – OC Chapter

Tuesday, October 07, 2014 Technical Meeting

Glass as a Core Packaging Platform for Next Generation Electronic Devices**Tim Mobley****CEO at Triton Microtechnologies****Abstract**

Glass is quickly becoming a dominant material choice driven by the need to have displays and electronics (primarily RF and analog) working within the same platform or form factor. The designer has many hurdles to overcome in order to successfully adopt glass as a core platform for integrating their designs. This presentation will explore glass as a core packaging platform, the motivations that are driving designers to consider glass, the technical challenges that have been solved, and the ones that remain a risk for certain applications. There will be an overall review of the many applications where glass can be used as a core platform.

Biography

Tim Mobley currently serves as CEO at Triton Microtechnologies, where they are focused on developing next generation packaging solutions based on glass. Mr. Mobley has previously held various positions with DuPont and Raytheon in the areas of RF design and development. He has extensive experience involving the manufacturing of advanced packaging technologies, primarily with ceramic, LTCC, and organic based materials. He has successfully commercialized several military and automotive radar innovations as well as developed technical and business relationships surrounding new product introduction. He holds a BS in Applied Physics.

Date: **Tuesday, October 07, 2014**

Location: **Broadcom Corporation, 5300 California Ave., Irvine, CA 92617 – “Salt Creek” in Bldg. 2**
Check in at the Security Gate and proceed to Bldg. 2. You will be escorted into the building.

Time: **5:30-6:00pm: Social time, 6:00-7:00pm: Presentation, 7:00pm: Dinner (free for attendees!)**

RSVP: **IEEE members and non-members all are welcome. Please RSVP at <http://tinyurl.com/o62byth>**
Please be at the Bldg. 2 entrance by 6:00 pm; no escorts after that. For questions regarding RSVP, please contact Zijie Cai (zijiecai@broadcom.com).

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